



TYPICAL PERFORMANCE CURVES

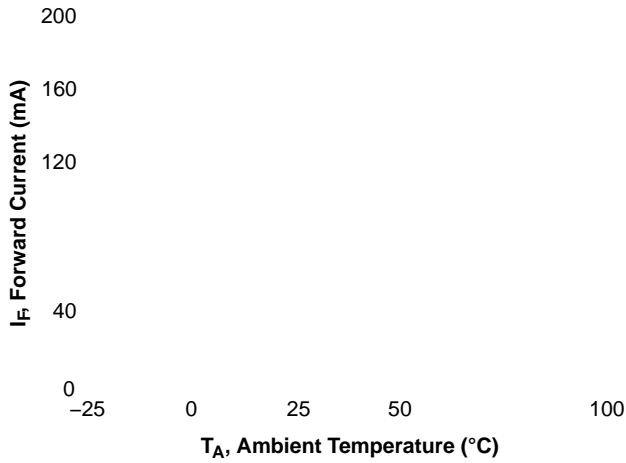


Figure 1. Maximum Forward Current vs. Temperature

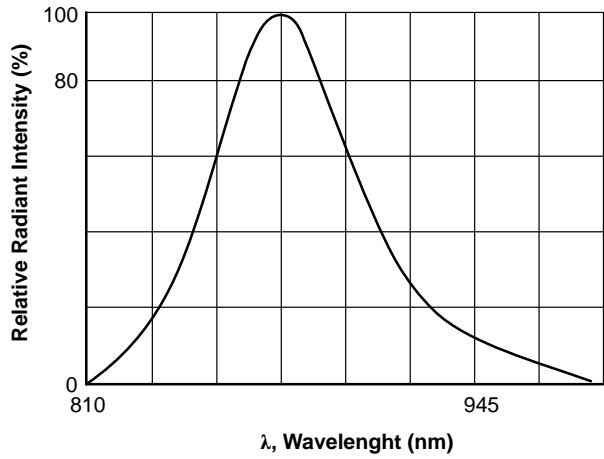


Figure 2. Relative Radiant Intensity vs. Wavelength

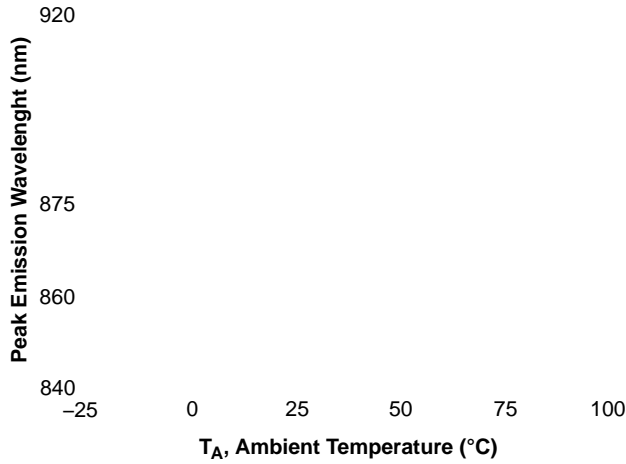


Figure 3. Peak Emission Wavelength vs. Ambient Temperature

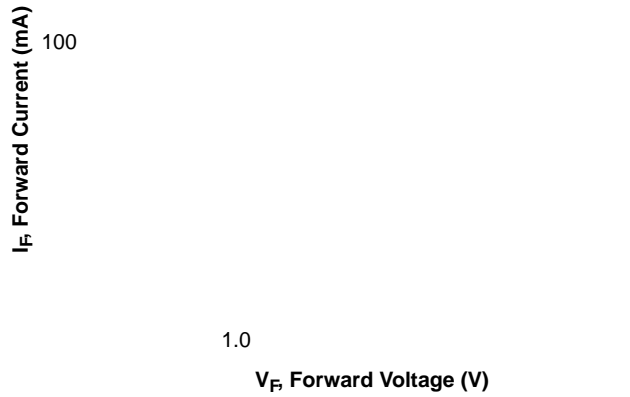


Figure 4. Forward Current vs. Forward Voltage

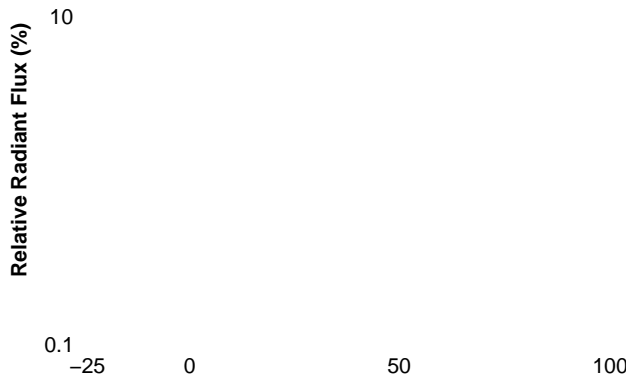


Figure 5. Relative Radiant Flux vs. Ambient Temperature

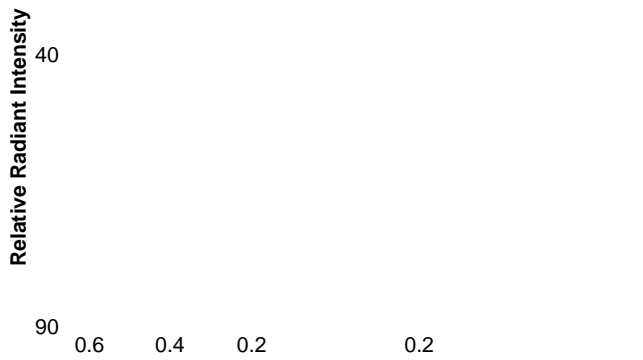


Figure 6. Relative Radiant Intensity vs. Angular Displacement

# QEB373

## ORDERING INFORMATION

Part Number	Package	Shipping <sup>†</sup>
QEB373	T-3/4, 2.50 × 2.00 (Case 100EE) (Pb-Free)	1000 Units / Bulk
QEB373GR	T-3/4, 2.50 × 2.00 (Case 100EF) (Pb-Free)	1000 / Tape & Reel
QEB373ZR	T-3/4, 2.50 × 2.00 (Case 100EG) (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

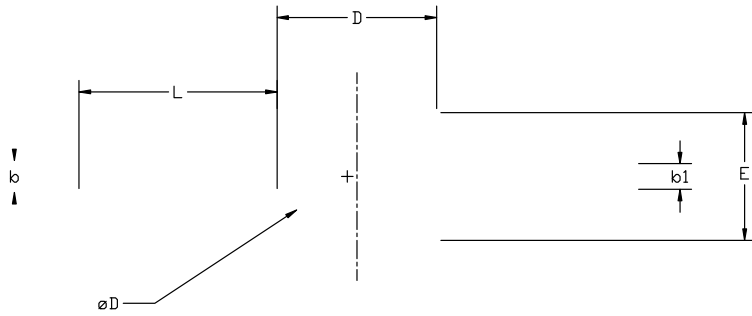


**T-3/4 2.50x2.00**  
**CASE 100EE**  
**ISSUE O**

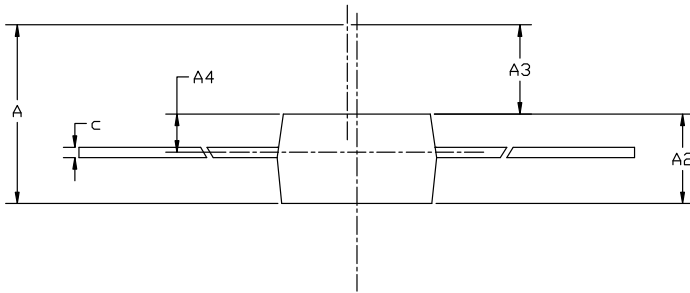
DATE 14 SEP 2023

NOTES:

1. CONTROLLING DIMENSIONS: MILLIMETERS
2. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
3. 2MM LED RP



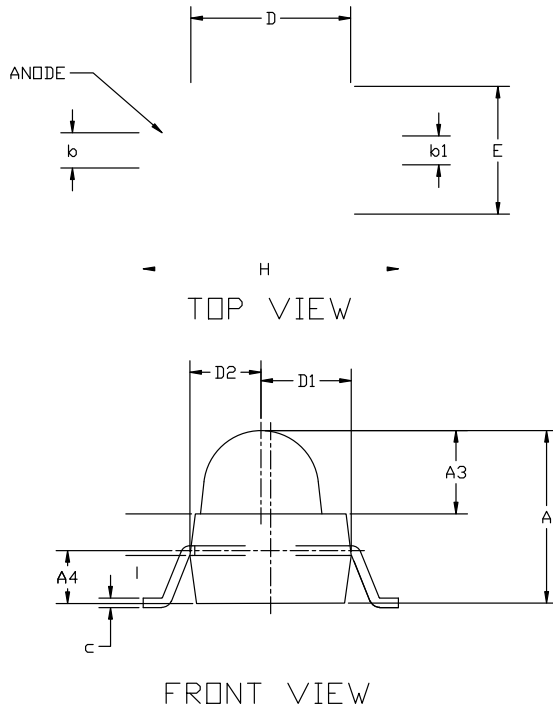
I DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	2.50	2.70	2.90
A2	1.2	1.40	
A3			
A4			
b		0.55	
b1		0.45	
c		0.15	
D		2.50	
E		2.00	
øD	7.00	---	---





T-3/4 2.50x2.00

JLLWING LED RP



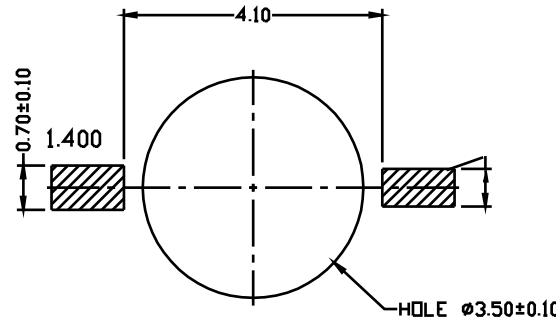
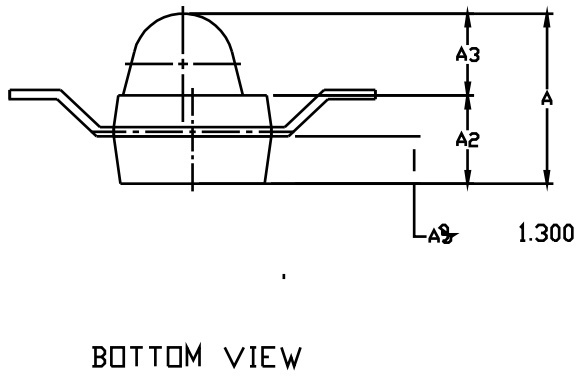
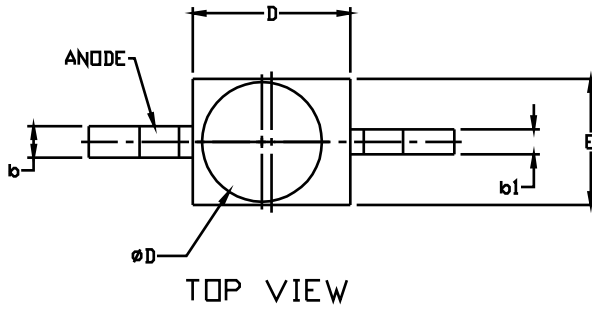
DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	2.50	2.70	2.90
A2	1.30	1.40	1.50
A3	1.20	1.30	1.40
A4	0.75	0.85	0.95
b	0.45	0.55	0.65
b1	0.35	0.45	0.55
c	0.10	0.15	0.20
D	2.30	2.50	2.70
D1	1.20	1.40	1.60
D2	0.90	1.10	1.30
E	1.80	2.00	2.20
H	3.80	4.00	4.20
L	0.20	0.30	0.40
$\varnothing D$	1.70	1.90	2.10
R1	0.70	0.80	0.90

LAND PATTERN  
P

\* For additional information on our  
Pb-Free strategy and soldering details,  
please download the ON Semiconductor  
Solderability

NOTES:

1. CONTROLLING DIMENSIONS: MILLIMETERS
2. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
3. 2MM ZBEND LED RP.



			.00
E	1.800	2.000	2.200
H	5.600	5.800	6.000
H1	4.100	4.300	4.500
H2	2.850	3.050	3.250
$\varnothing D$	1.700	1.900	2.100
R1	0.700	0.800	0.900

Mounting  
TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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